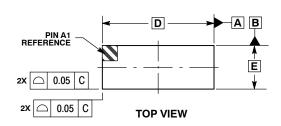
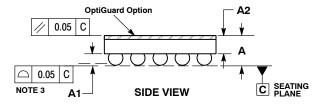


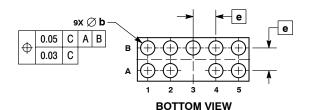


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DATE 26 JUL 2010





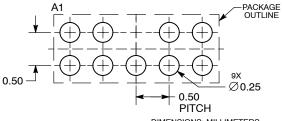


NOTES:

- DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 COPLANARITY APPLIES TO SPHERICAL
 CROWNS OF SOLDER BALLS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.56	0.72	
A1	0.21	0.27	
A2	0.42 REF		
b	0.29	0.35	
D	2.47 BSC		
Е	0.97 BSC		
_	0.50.BSC		

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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